

**REMARKS**

**Summary of the Office Action**

Claims 1 and 8 stand rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claims 1, 3 and 8-15 stand rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over *Lee* (USPN 6,410,414) in view of *Braeckelmann et al.* (USPN 6,218,302).

**Summary of the Response to the Office Action**

Applicants amended claims 1 and 8. Accordingly, claims 1, 3 and 8-15 are presently pending.

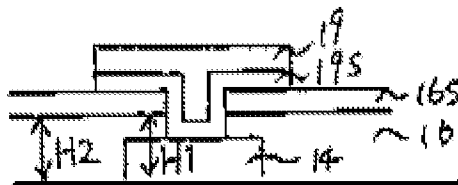
**Rejection Under 35 U.S.C. § 112**

Claims 1 and 8 stand rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. Although Applicants respectfully disagree, Applicants amend claims 1 and 8, without prejudice or disclaimer, to advance prosecution. Accordingly, Applicants respectfully assert that the rejection should be withdrawn.

**All Claims Define Allowable Subject Matter**

Claims 1, 3, 8 and 10-15 stand rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over *Lee* (USPN 6,410,414) in view of *Braeckelmann et al.* (USPN 6,218,302). Applicants respectfully traverse the rejection for at least the following reasons.

Independent claims 1 and 8, as amended, recite “wherein the inter layer dielectric includes a first inter layer dielectric formed on the first interconnect layer and a second inter layer dielectric formed on a periphery of the first interconnect layer, and the first inter layer dielectric is thinner than the second inter layer dielectric, and wherein a sum of a thickness of the first interconnect layer and a thickness of the first inter layer dielectric is substantially same as a thickness of the second inter layer dielectric.” No new matter has been entered. *See* FIGs. 1 and 5. For clarification, the sum of a thickness of the first interconnect layer and a thickness of the first inter layer dielectric (H1), and the thickness of the second inter layer dielectric (H2) are shown in the figure below.



Applicants respectfully assert that *Lee* and *Braeckelmann et al.* are silent as to “wherein the inter layer dielectric includes a first inter layer dielectric formed on the first interconnect layer and a second inter layer dielectric formed on a periphery of the first interconnect layer, and the first inter layer dielectric is thinner than the second inter layer dielectric, and wherein a sum of a thickness of the first interconnect layer and a thickness of the first inter layer dielectric is substantially same as a thickness of the second inter layer dielectric,” as required by independent claims 1 and 8, as amended.

In addition, independent claims 1 and 8, as previously presented, recite that the metal interconnect layer consists of gold material and serves as a bonding pad and that a planarized

polyimide directly surrounds the metal interconnect layer including a surface and a side wall thereof. Pages 3 and 4 of the Office Action admit that *Lee* fails to teach these features.

Nevertheless, the Office Action alleges that *Braeckelmann et al.* remedies the deficiencies of *Lee* alleging that the conductive film 83 of *Braeckelmann et al.* is the “metal interconnect layer,” as claimed, and that the passivation layer 1001 and the polyimide film 1002 of *Braeckelmann et al.* are the “planarized polyimide,” as claimed. Applicants respectfully disagree.

First, Applicants respectfully assert that the passivation layer 1001 of *Braeckelmann et al.* is not made of polyimide, but is made of silicon oxynitride and nitride. *See* col. 8, lines 21 to 24 of *Braeckelmann et al.* Further, assuming *arguendo*, that the passivation layer 1001 of *Braeckelmann et al.* is a polyimide, Applicants respectfully assert that the passivation layer 1001 merely covers a surface of the conductive film 83, i.e., not “a surface and a side wall thereof,” as required by independent claims 1 and 8. In addition, Applicants respectfully assert that the polyimide film 1002 of *Braeckelmann et al.* does not cover “a surface and a side wall thereof,” as required by independent claims 1 and 8.

Accordingly, Applicants respectfully assert that independent claim 1 and 8, and hence dependent claims 3 and 9-15 are allowable.

**Conclusion**

In view of the foregoing, Applicants respectfully request reconsideration and the timely allowance of the pending claims. Should the Examiner feel that there are any issues outstanding after consideration of this response, the Examiner is invited to contact Applicants' undersigned representative to expedite prosecution.

If there are any other fees due in connection with the filing of this response, please charge the fees to our Deposit Account No. 50-0310. If a fee is required for an extension of time under 37 C.F.R. § 1.136 not accounted for above, such an extension is requested and the fee should also be charged to our Deposit Account.

Respectfully submitted,

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